

SOT1156-1

plastic, thermal enhanced extremely thin small outline package; 12 terminals; 0.4 mm pitch; 2.5 mm x 2.1 mm x 0.5 mm body

30 January 2017

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2521-12
Package type industry code	DFN2521-12
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	17-9-2010
Manufacturer package code	SOT1156

Table 1. Package summary

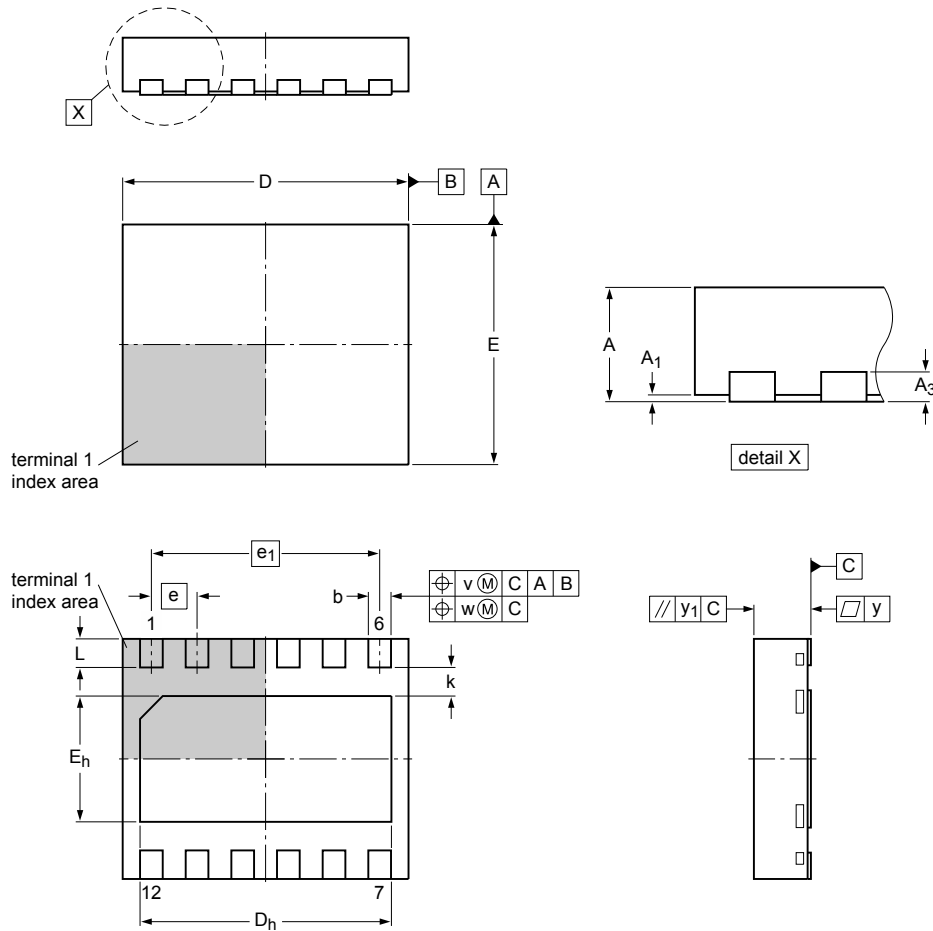
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	2	-	2.1	2.2	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	12	-	

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2. Package outline

Plastic, thermal enhanced extremely thin small outline package; no leads; 12 terminals; body 2.1 x 2.5 x 0.5 mm

SOT1156-1



Dimensions

Unit ⁽¹⁾	A	A ₁	A ₃	b	D	D _h	E	E _h	e	e ₁	k	L	v	w	y	y ₁
max	0.5	0.05		0.25	2.6	2.25	2.2	1.15				0.30				
mm nom			0.127	0.20	2.5	2.20	2.1	1.10	0.4	2		0.25	0.1	0.05	0.05	0.05
min		0.00		0.15	2.4	2.15	2.0	1.05			0.2	0.20				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sol1156-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1156-1	---	---	---		10-09-17 12-05-22

Fig. 1. Package outline DFN2521-12 (SOT1156-1)

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3. Soldering

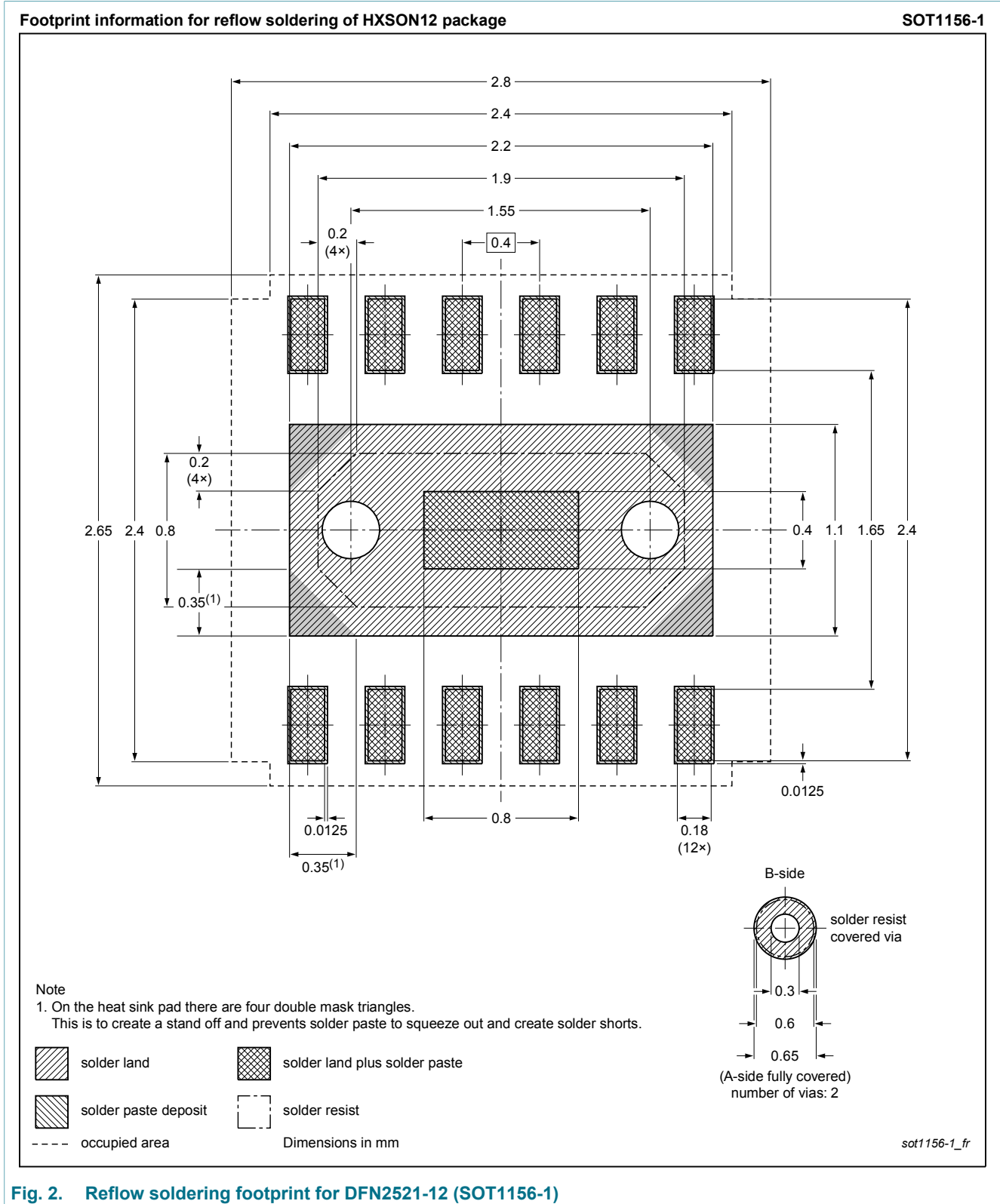


Fig. 2. Reflow soldering footprint for DFN2521-12 (SOT1156-1)

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4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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